

Multilayer Power Inductor

CIG22L Series (2520/ EIA 1008)



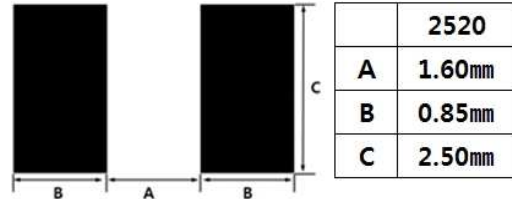
APPLICATION

Mobile phones, DSC, DVC, PDA etc. for DC-DC Converter

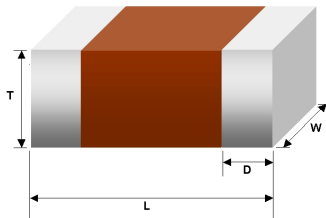
FEATURES

- Low DC resistance
- Magnetically shielded structure
- Free of all RoHS-regulated substances
- Monolithic structure for high reliability

RECOMMENDED LAND PATTERN



DIMENSION



TYPE	Dimension [mm]			
	L	W	T	D
22	2.5±0.2	2.0±0.2	0.9±0.1	0.55±0.25

DESCRIPTION

Part no.	Size (inch/mm)	Inductance (uH)@1MHz	DC Resistance(Ω)	Rated Current (A) Max.
CIG22LR47MNE	1008/2520	0.47 ±20 %	0.040 ±25 %	1.80
CIG22L1R0MNE	1008/2520	1.0 ±20 %	0.060 ±25 %	1.60
CIG22L1R2MNE	1008/2520	1.2 ±20 %	0.065 ±25 %	1.50
CIG22L1R5MNE	1008/2520	1.5 ±20 %	0.070 ±25 %	1.50
CIG22L2R2MNE	1008/2520	2.2 ±20 %	0.080 ±25 %	1.30
CIG22L3R3MNE	1008/2520	3.3 ±20 %	0.100 ±25 %	1.20
CIG22L4R7MNE	1008/2520	4.7 ±20 %	0.110 ±25 %	1.10
CIG22L6R8MNE	1008/2520	6.8 ±20 %	0.203 ±30 %	0.80
CIG22L100MNE	1008/2520	10.0 ±20 %	0.323 ±30 %	0.60

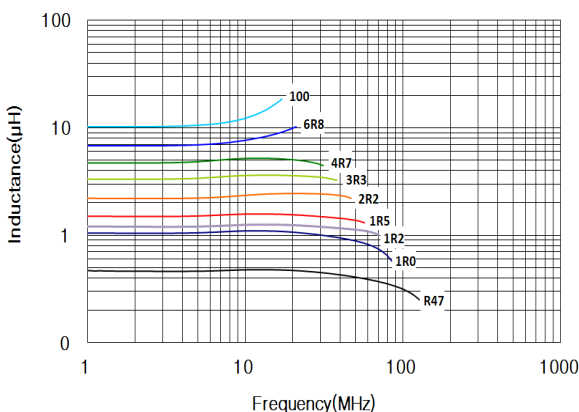
※ Rated Current (A): DC current value when the self-generation of heat rises to 40℃ (Reference ambient temperature:25℃)

※ Operating temperature range: -40 to +125℃ (Including self-temperature rise)

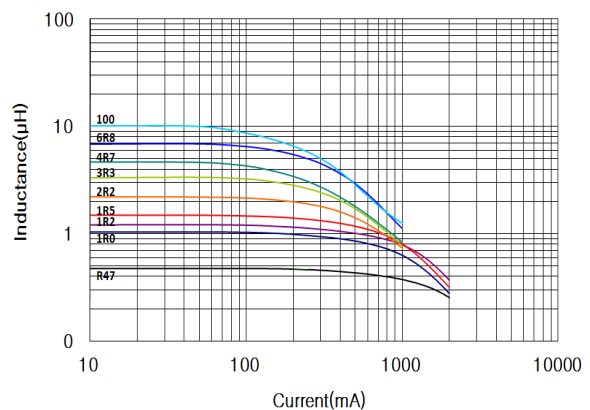
※ Test equipment: Agilent :E4991A+16092A

CHARACTERISTIC DATA

1) Frequency characteristics (Typ.)



2) DC Bias characteristics (Typ.)



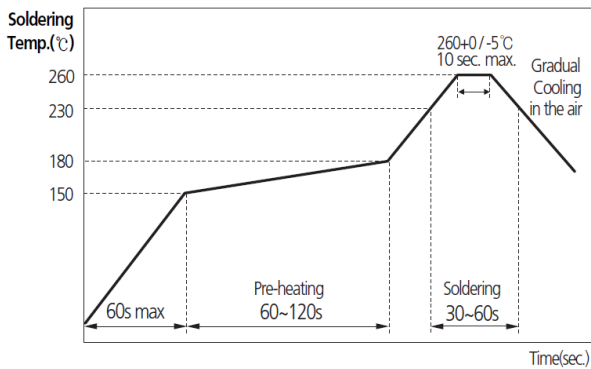
PRODUCT IDENTIFICATION

CI G 22 L 1R0 M N E
(1) (2) (3) (4) (5) (6) (7) (8)

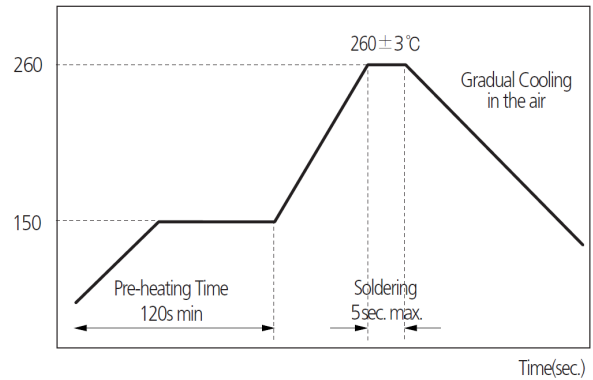
- (1) Chip Inductor
- (2) Power Inductor
- (3) Dimension
- (4) Product Series (L: Low Rdc)
- (5) Inductance (1R0:1.0uH)
- (6) Tolerance (M:±20%)
- (7) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (8) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Embossed Taping	3,000

Any data in this sheet are subject to change, modify or discontinue without notice. The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.